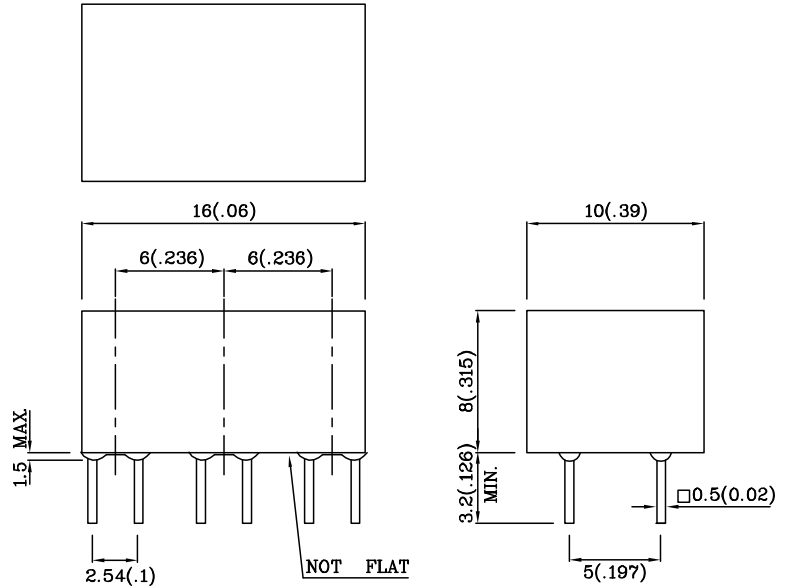


Features

- UNIFORM LIGHT EMITTING AREA.
- EASILY MOUNTED ON P.C. BOARDS OR INDUSTRY STANDARD SOCKETS.
- FLUSH MOUNTABLE.
- EXCELLENT ON/OFF CONTRAST.
- CAN BE USED WITH PANELS AND LEGEND MOUNTS.
- MECHANICALLY RUGGED.
- I.C. COMPATIBLE.
- BOTTOM SURFACE OF EPOXY IS NOT FLAT.
- RoHS COMPLIANT.



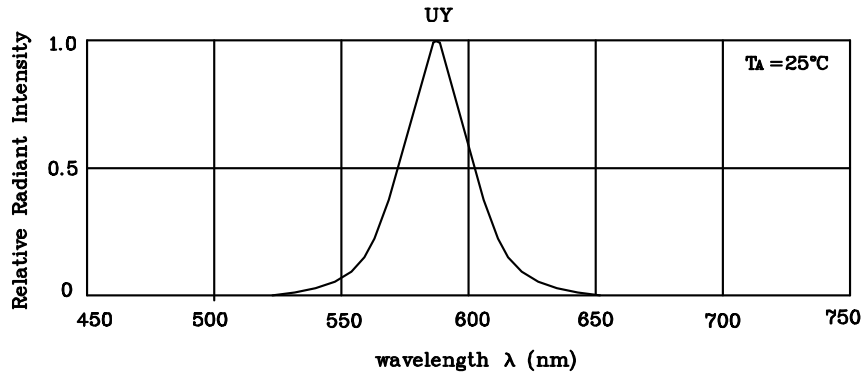
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.

Absolute Maximum Ratings (TA=25°C)		UY (GaAsP/GaP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	140	mA
Power Dissipation	P _T	105	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

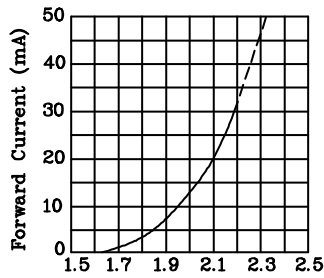
Operating Characteristics (TA=25°C)		UY (GaAsP/ GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	1.95	V
Forward Voltage (Max.) (I _F =10mA)	V _F	2.5	V
Reverse Current (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission (I _F =10mA)	λ peak	590	nm
Wavelength of Dominant Emission (I _F =10mA)	λ D	588	nm
Spectral Line Full Width At Half-Maximum (I _F =10mA)	Δλ	35	nm
Capacitance (V _F =0V, f=1MHz)	C	20	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =10mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XEUY26D	Yellow	GaAsP/GaP	Yellow Diffused	5	9	590	120°
Published Date : MAY.30.2005 Drawing No : XDSA1950 V3 Checked : B.L.LIU P.1/3							

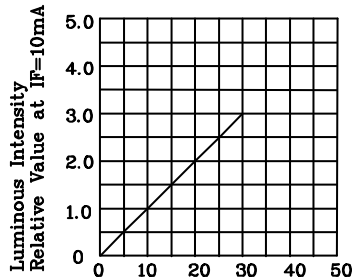


RELATIVE INTENSITY Vs. WAVELENGTH

❖ UY



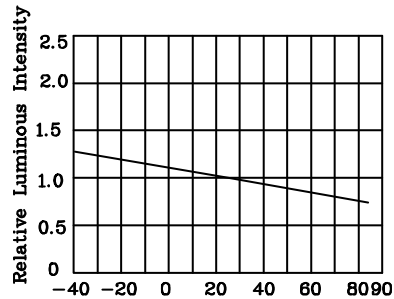
Forward Voltage(V)
FORWARD CURRENT Vs.
FORWARD VOLTAGE



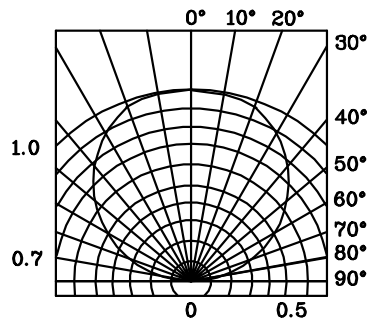
I_f -Forward Current (mA)
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



Ambient Temperature T_A ($^\circ\text{C}$)
FORWARD CURRENT
DERATING CURVE

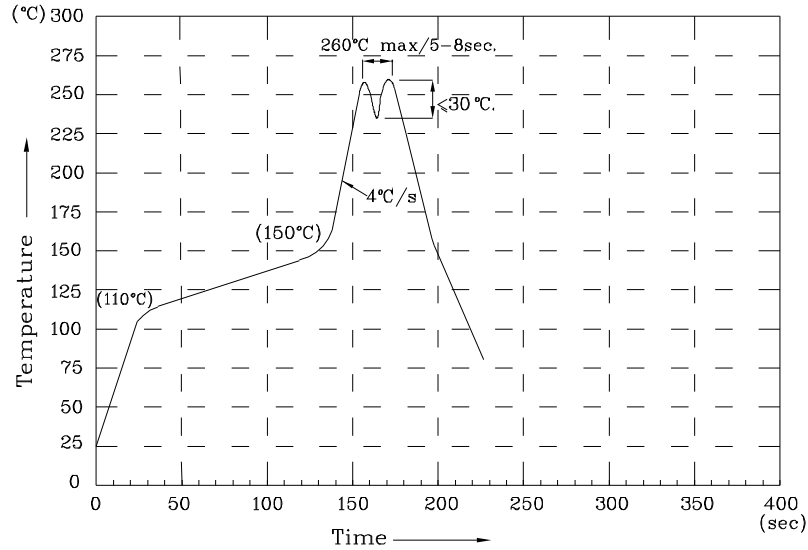


Ambient Temperature T_A ($^\circ\text{C}$)
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.